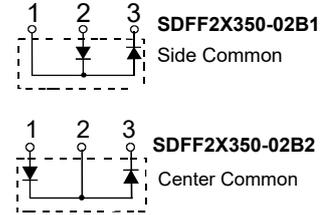
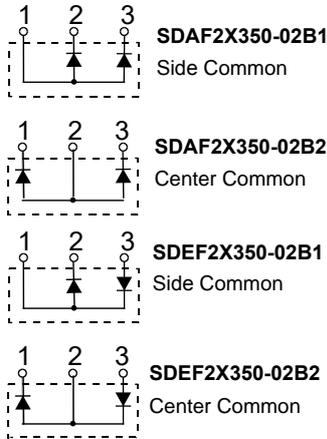
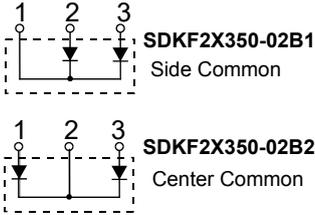


# SDKF2X350-02B

## Soft Recovery Behaviour Ultra Fast Recovery Epitaxial Diode Modules



	VRSM V	VRRM V
SDKF2x350-02B1	200	200
SDKF2x350-02B2	200	200

	VRSM V	VRRM V
SDAF2x350-02B1	200	200
SDAF2x350-02B2	200	200

	VRSM V	VRRM V
SDF2x350-02B1	200	200
SDF2x350-02B2	200	200

	VRSM V	VRRM V
SDEF2x350-02B1	200	200
SDEF2x350-02B2	200	200

Symbol	Test Conditions	Maximum Ratings	Unit
<b>IFRMS</b> <b>IFAVM</b> <b>IFRM</b>	$T_C=75^\circ\text{C}$ $T_C=75^\circ\text{C}$ ; rectangular, $d=0.5$ , per chip $t_p < 10\mu\text{s}$ ; rep. rating, pulse width limited by $T_{VJM}$	550 350 1800	A
<b>IFSM</b>	$T_{VJ}=45^\circ\text{C}$ $t=10\text{ms}$ (50Hz), sine $t=8.3\text{ms}$ (60Hz), sine	5400 2640	A
	$T_{VJ}=150^\circ\text{C}$ $t=10\text{ms}$ (50Hz), sine $t=8.3\text{ms}$ (60Hz), sine	2160 2380	
<b><math>I^2t</math></b>	$T_{VJ}=45^\circ\text{C}$ $t=10\text{ms}$ (50Hz), sine $t=8.3\text{ms}$ (60Hz), sine	28800 29300	$\text{A}^2\text{s}$
	$T_{VJ}=150^\circ\text{C}$ $t=10\text{ms}$ (50Hz), sine $t=8.3\text{ms}$ (60Hz), sine	23300 23800	
<b><math>T_{VJ}</math></b> <b><math>T_{stg}</math></b> <b><math>T_{Smax}</math></b>		-40...+150 -40...+125 110	$^\circ\text{C}$
<b><math>P_{tot}</math></b>	$T_C=25^\circ\text{C}$	875	W
<b><math>V_{ISOL}</math></b>	50/60Hz, RMS $t=1\text{min}$ $I_{ISOL} \leq 1\text{mA}$ $t=1\text{s}$	3000 3600	V~
<b><math>M_d</math></b>	Mounting torque (M6) Terminal connection torque (M6)	2.25-2.75/20-25 4.50-5.50/40-48	Nm/lb.in.
<b>ds</b> <b>dA</b> <b>a</b>	Creeping distance on surface Strike distance through air Maximum allowable acceleration	12.7 9.6 50	mm mm $\text{m/s}^2$
<b>Weight</b>		150	g



# SDKF2X350-02B

## Soft Recovery Behaviour Ultra Fast Recovery Epitaxial Diode Modules

Symbol	Test Conditions	Characteristic Values		Unit
		typ.	max.	
$I_R$	$T_{VJ}=25^{\circ}\text{C}; V_R=V_{RRM}$		3	mA
	$T_{VJ}=25^{\circ}\text{C}; V_R=0.8 \cdot V_{RRM}$		2	
	$T_{VJ}=125^{\circ}\text{C}; V_R=0.8 \cdot V_{RRM}$		80	
$V_F$	$I_F=175\text{A}; T_{VJ}=125^{\circ}\text{C}$		0.80	V
	$T_{VJ}=25^{\circ}\text{C}$		0.98	
	$I_F=350\text{A}; T_{VJ}=125^{\circ}\text{C}$		0.92	
	$T_{VJ}=25^{\circ}\text{C}$		1.07	
$V_{TO}$	For power-loss calculations only		0.53	V
$r_T$			1.29	m $\Omega$
$R_{thJH}$	DC current		0.228	K/W
$R_{thJC}$	DC current		0.143	
$t_{rr}$	$I_F=350\text{A}; T_{VJ}=100^{\circ}\text{C}$	150	200	ns
$I_{RM}$	$V_R=100\text{V}; T_{VJ}=25^{\circ}\text{C}$		9	A
	$-di/dt=200\text{A}/\mu\text{s}; T_{VJ}=100^{\circ}\text{C}$		15	A

### FEATURES

- \* International standard package
- \* Copper Baseplate
- \* Planar passivated chips
- \* Short recovery time
- \* Low switching losses
- \* Soft recovery behaviour
- \* Isolation voltage 3600 V~
- \* RoHS compliant

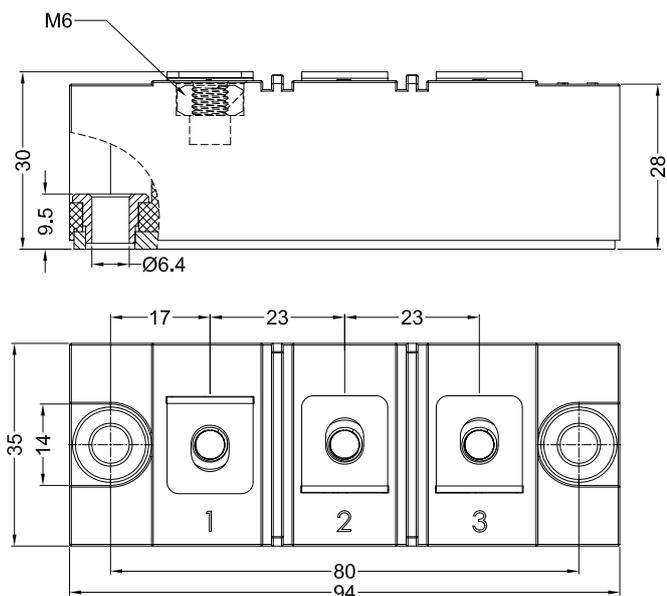
### APPLICATIONS

- \* Antiparallel diode for high frequency switching devices
- \* Free wheeling diode in converters and motor control circuits
- \* Inductive heating and melting
- \* Uninterruptible power supplies (UPS)
- \* Ultrasonic cleaners and welders

### ADVANTAGES

- \* High reliability circuit operation
- \* Low voltage peaks for reduced protection circuits
- \* Low noise switching
- \* Low losses

### Dimensions in mm



# SDKF2X350-02B

## Soft Recovery Behaviour Ultra Fast Recovery Epitaxial Diode Modules

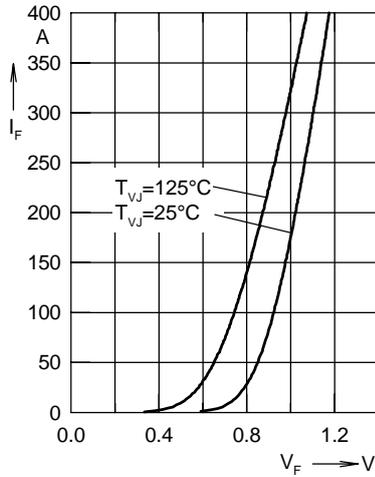


Fig. 1 Forward current  $I_F$  versus voltage drop  $V_F$  per leg

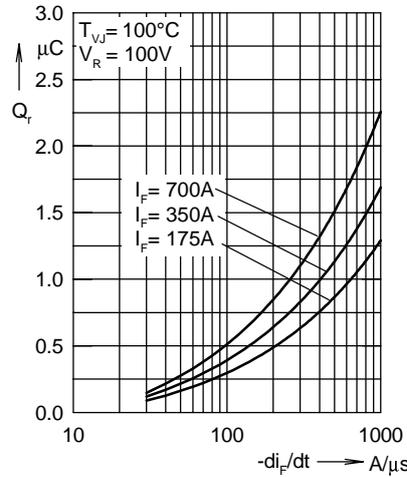


Fig. 2 Reverse recovery charge  $Q_r$  versus  $-di_F/dt$

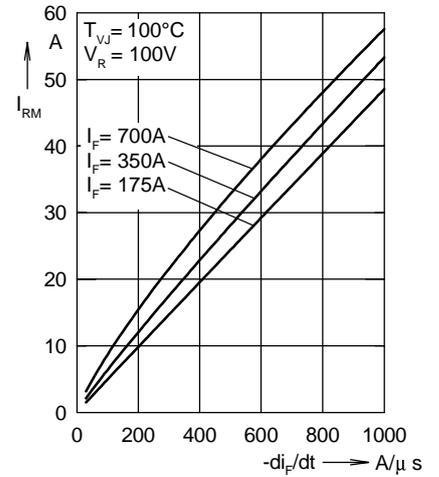


Fig. 3 Peak reverse current  $I_{RM}$  versus  $-di_F/dt$

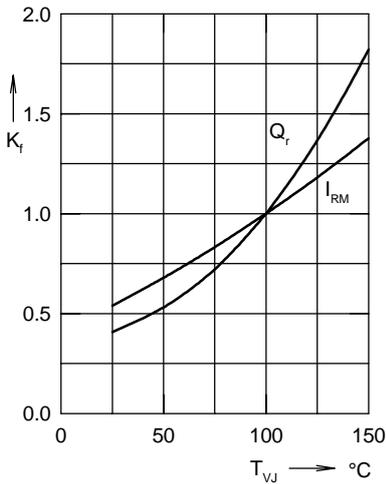


Fig. 4 Dynamic parameters  $Q_r$ ,  $I_{RM}$  versus junction temperature  $T_{VJ}$

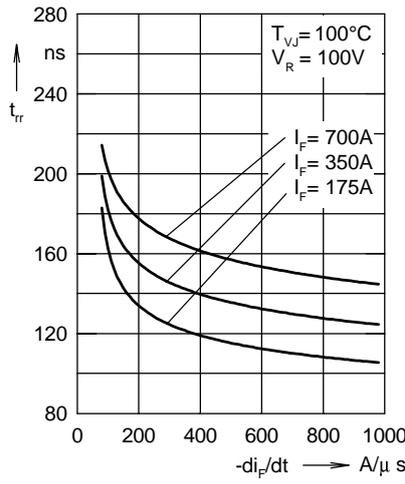


Fig. 5 Recovery time  $t_{tr}$  versus  $-di_F/dt$

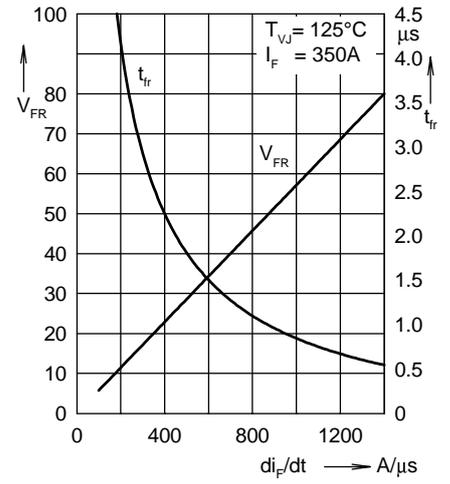


Fig. 6 Peak forward voltage  $V_{FR}$  and  $t_{tr}$  versus  $di_F/dt$

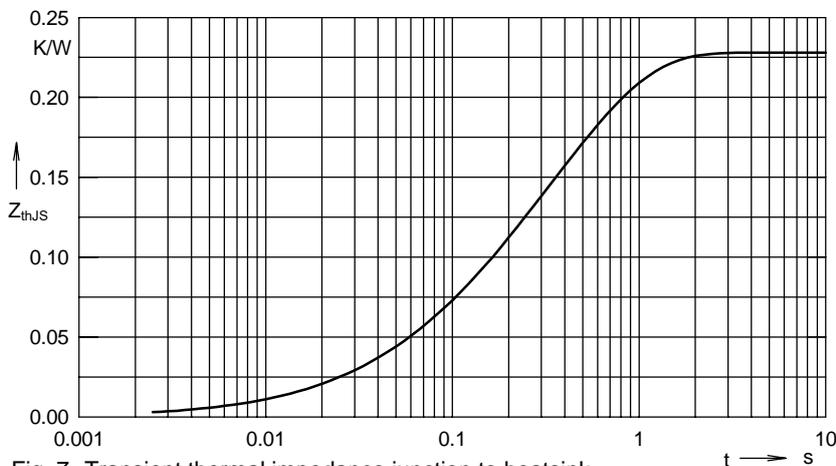


Fig. 7 Transient thermal impedance junction to heatsink

Constants for  $Z_{thJS}$  calculation:

i	$R_{thi}$ (K/W)	$t_i$ (s)
1	0.002	0.08
2	0.008	0.024
3	0.054	0.112
4	0.164	0.464